

1		2		3		4		5		6		7		8	
RoHs												VER		MARK	
												PR. BY		DESCRIP TION	
												DATE			

16.95
15.60
10.90
3.50
2.65
6.35
1.27
0.45X6
C5 C1 C6 C2 C7 C3
Center Line
C1 C2 C3
C5 C6 C7
MICRO SIM CARD
0.30±0.2 PUSH STROKE POSITION
1.20±0.15 CARD LOCK POSITION
3.75±0.2 CARD EJECT POSITION
17.20
17.20
1.35±0.1
0.10
16.37
1.35
GND
12.68
2.00
GND
1.62
0.53

16.36
15.40
15.30
12.15
1.22
0.37
0.40±0.05
CARD CENTER
CONNECTOR CENTER
1.38

15.00 Micro SIM
12.30 Nano SIM
8.80 Nano sim
12.00 Micro SIM
C1 C5
C2 C6
C3 C7
C4 C8
Nano SIM
Micro SIM
0.68

3.10
1.35(6X)
1.52
6.35
1.27(5X)
1.10(4X)
2.60
0.90(6X)
8.25
0.55
2.60
12.68
2.90
GND
15.35
16.45
2.90
GND
PAD AREA
KEEP OUT AREA
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

MATERIAL:
INSULATOR: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0
CONTACT: COPPER ALLOY
SHELL: SUS
PLATING:
CONTACT: PLATED 50U" NI OVER ALL CONTACT AU 1U
SHELL: PLATED 50U" NI OVERALL
PLATED 1U" AU SELECTIVE CONTACT AREA
ELECTRICAL:
CURRENT RATING: 0.5MA
VOLTAGE RATING: 5V AC/DC
AMBIENT TEMPERATURE RANGE: -40℃ ~ +85℃
STORAGE TEMPERATURE RANGE: -40℃ ~ +85℃
AMBIENT HUMIDITY RANGE: 95% R.H. MAX.
CONTACT RESISTANCE: 100M MAX. Ω
INSULATION RESISTANCE: 1000M MIN./500VDC Ω
REFLOW PEAK TEMP: 260℃
MATING CYCLES: 5000MIN INSERTIONS
Salt spray time: 24H

Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

16.36
15.40
15.30
12.15
1.22
0.37
0.40±0.05
CARD CENTER
CONNECTOR CENTER
1.38

15.00 Micro SIM
12.30 Nano SIM
8.80 Nano sim
12.00 Micro SIM
C1 C5
C2 C6
C3 C7
C4 C8
Nano SIM
Micro SIM
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PAD AREA
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RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

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C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

GENERAL TOLERANCES
UNLESS SPECIFIED

X.X	±0.30	X.°	±5°
.XX	±0.20	X.X°	±1°
.XXX	±0.10	X.XX°	±0.5°

MANUFACTURE DWG

深圳市华明通电子有限公司
Shenzhen Huamingtong Electronics Co., Ltd

PART NO.
MICRO SIM 7P 1.35H

TITLE:
MICRO SIM CARD PUSH
PUSH 6PIN H1.35

DESIGN: James

CUSTOMER

SIZE
A4

UNITS
MM

CHED: Talen

APPD: Sophia

SCALE
N:A

SHEET
1/1

1		2		3		4		5		6		7		8	
RoHs												VER		MARK	
												PR. BY		DESCRIP TION	
												DATE			

16.95
15.60
10.90
3.50
2.65
6.35
1.27
0.45X6
C5 C1 C6 C2 C7 C3
Center Line
C1 C2 C3
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0.30±0.2 PUSH STROKE POSITION
1.20±0.15 CARD LOCK POSITION
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17.20
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GND
12.68
2.00
GND
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0.53

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15.40
15.30
12.15
1.22
0.37
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CARD CENTER
CONNECTOR CENTER
1.38

15.00 Micro SIM
12.30 Nano SIM
8.80 Nano sim
12.00 Micro SIM
C1 C5
C2 C6
C3 C7
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Nano SIM
Micro SIM
0.68

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2.90
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PAD AREA
KEEP OUT AREA
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

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C3	CLK OF SIM
C5	GND OF SIM
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C7	I/O OF SIM
C4/C8	N/A

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15.40
15.30
12.15
1.22
0.37
0.40±0.05
CARD CENTER
CONNECTOR CENTER
1.38

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12.30 Nano SIM
8.80 Nano sim
12.00 Micro SIM
C1 C5
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Nano SIM
Micro SIM
0.68

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PAD AREA
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RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

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C6	VPP OF SIM
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C4/C8	N/A

GENERAL TOLERANCES
UNLESS SPECIFIED

X.X	±0.30	X.°	±5°
.XX	±0.20	X.X°	±1°
.XXX	±0.10	X.XX°	±0.5°

MANUFACTURE DWG

深圳市华明通电子有限公司
Shenzhen Huamingtong Electronics Co., Ltd

PART NO.
MICRO SIM 7P 1.35H

TITLE:
MICRO SIM CARD PUSH
PUSH 6PIN H1.35

DESIGN: James

CUSTOMER

SIZE
A4

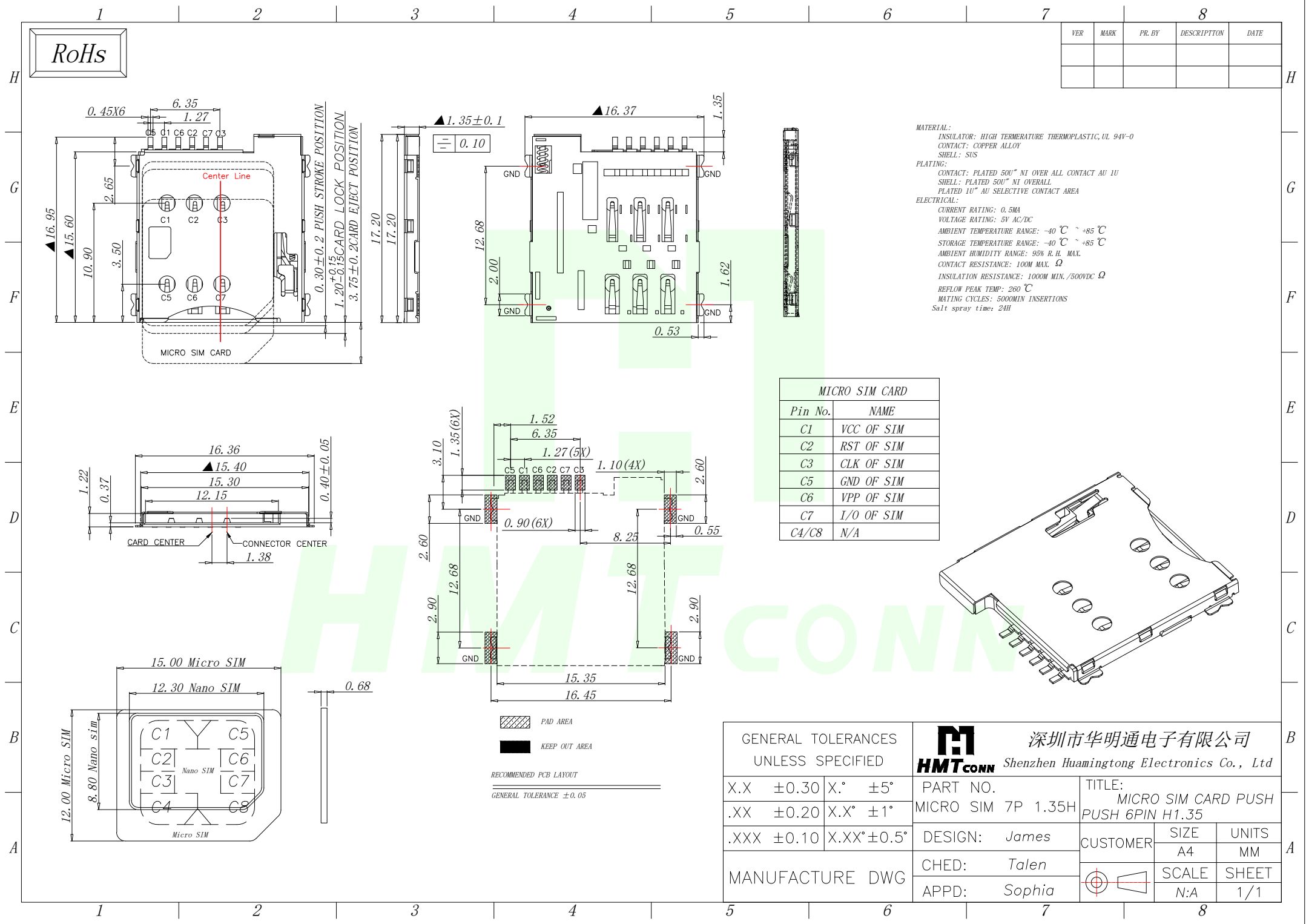
UNITS
MM

CHED: Talen

APPD: Sophia

SCALE
N:A

SHEET
1/1

[illegible]

1		2		3		4		5		6		7		8	
RoHs												VER		MARK	
												PR. BY		DESCRIP TION	
														DATE	

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INSULATION RESISTANCE: 1000M MIN./500VDC Ω
REFLOW PEAK TEMP: 260℃
MATING CYCLES: 5000MIN INSERTIONS
Salt spray time: 24H

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C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

GENERAL TOLERANCES UNLESS SPECIFIED	
X.X ±0.30	X.° ±5°
.XX ±0.20	X.X° ±1°
.XXX ±0.10	X.XX° ±0.5°

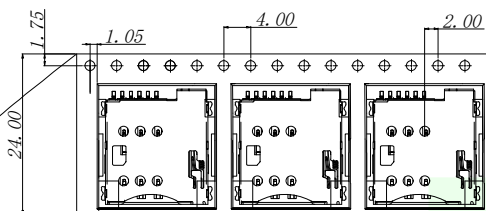
PART NO.		TITLE:	
MICRO SIM 7P 1.35H		MICRO SIM CARD PUSH PUSH 6PIN H1.35	
DESIGN:	James	CUSTOMER	SIZE
CHED:	Talen		A4
APPD:	Sophia		MM

SCALE	SHEET
N:A	1/1

RoHs

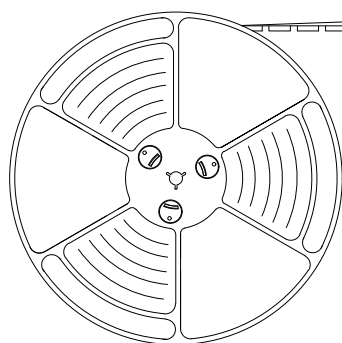
VER	MARK	PR. BY	DESCRIPTION	DATE

客户拉出方向



客户拉出方向

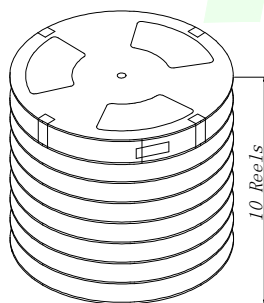
自粘上贴



纸箱底部和顶部
各垫一块珍珠棉

护角

纸箱

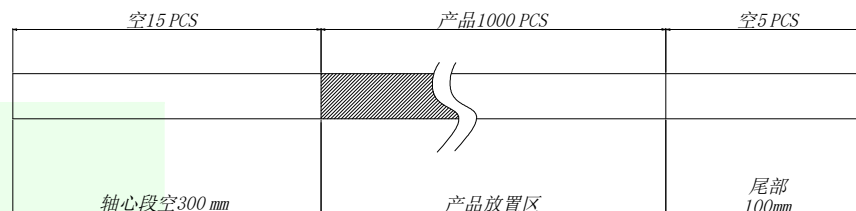


外箱标签贴示位置

NOTES

1. 每卷包装数量: 1000 PCS/ 每卷

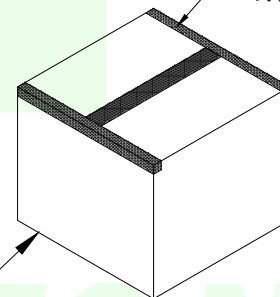
2. 卷带包装方式:



3. 每箱包装数量: 10000PCS/ 箱

4. 纸箱 350mm*350mm*440mm (内部尺寸), 材质 K=K

封箱胶带



将10卷产品放入箱内

GENERAL TOLERANCES
UNLESS SPECIFIED

X.X	±0.30	X.°	±5°
.XX	±0.20	X.X°	±1°
.XXX	±0.10	X.XX°	±0.5°

MANUFACTURE DWG



深圳市华明通电子有限公司

Shenzhen Huamingtong Electronics Co., Ltd

PART NO.
MICRO SIM 7P 1.35H

TITLE:
MICRO SIM CARD PUSH
PUSH 6PIN H1.35

DESIGN: James

CHED: Talen

APPD: Sophia

CUSTOMER

SIZE
A4

UNITS
MM

SCALE

SHEET

N:A 1/1